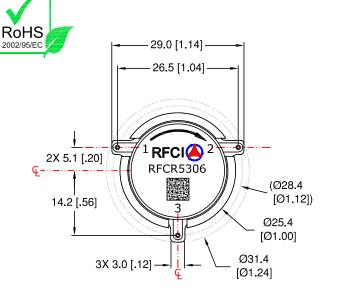


DWG. NO.

REV

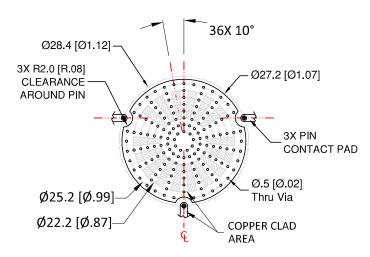


Ø25.4 [1.00]

Ø23.5 [.93]

3X Ø1.2 [.05]

ONLY BE INCORPORATED AS DIRECTED BY THE DESIGN ACTIVITY.



SolderMask Pattern

### Recommended Footprint Copper-SolderMask Pattern

The Land Pattern should be with good thermal conductivity

#### Finish:

- 1. Housing: Silver plated 2. Pin: Gold plated
- 3. Coplanarity specification: 0.10 [.004] MAX.

# **Specifications**

8.5 [.33]

Parameter	Minimum	Typical	Maximum
Frequency Range (MHz)	1200		1400
Insertion Loss (dB)		< .25	.35
Isolation (dB)	20	> 23	
Return Loss (dB)	20	> 23	

3X PIN

SEE FINISH

## Power & Temperature Ratings

Parameter	Maximum
Forward PWR Peak/AVG	500/100 Watts
Reverse Power CW	100 Watts
Operating Temperature	-40 to +85° C
Storage Temperature	-50 to +125° C

#### NOTES:

- 1. Typical Values Represent Performance @ +23 °C.
- 2. S-Parameters to be measured by connecting Port 1 and 2 to VNA, and Port 3 to Load with return loss 30dB or higher

### CW SMD CIRCULATOR MODEL: RFCR5306

